



# 175°C 40V P-CHANNEL ENHANCEMENT MODE MOSFET PowerDI5060-8

#### **Product Summary**

BV <sub>DSS</sub>	RDS(ON) Max	I <sub>D</sub> Tc = +25°C
-40V	13mΩ @ V <sub>GS</sub> = -10V	-69A
-40 V	23mΩ @ V <sub>GS</sub> = -4.5V	-52A

#### **Features and Benefits**

- Rated to +175°C Ideal for High Ambient Temperature Environments
- 100% Unclamped Inductive Switch (UIS) Test in Production
- Low On-Resistance
- Fast Switching Speed
- Lead-Free Finish; RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- The DMPH4013SPSQ is suitable for automotive applications requiring specific change control; this part is AEC-Q101 qualified, PPAP capable, and manufactured in IATF 16949 certified facilities.

https://www.diodes.com/quality/product-definitions/

### **Description and Applications**

This MOSFET is designed to meet the stringent requirements of Automotive applications. It is qualified to AEC-Q101, supported by a PPAP and is ideal for use in:

- Reverse Polarity Protection
- BLDC Motor Control
- Power Management Functions

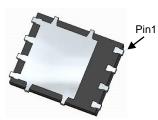
#### **Mechanical Data**

- Case: PowerDI<sup>®</sup>5060-8
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminal Connections: See Diagram
- Terminals: Finish 100% Matte Tin Annealed over Copper Leadframe. Solderable per MIL-STD-202, Method 208<sup>3</sup>
- · Weight: 0.097 grams (Approximate)

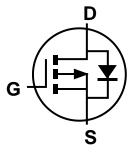




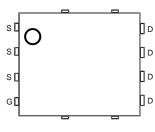
Top View



**Bottom View** 



Internal Schematic



Top View Pin Configuration

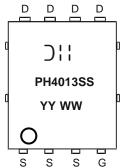
#### Ordering Information (Note 4)

Part Number	Case	Packaging	
DMPH4013SPSQ-13	PowerDI5060-8	2,500 / Tape & Reel	

Notes:

- 1. EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant. All applicable RoHS exemptions applied.
- See https://www.diodes.com/quality/lead-free/ for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at https://www.diodes.com/design/support/packaging/diodes-packaging/.

#### **Marking Information**



);; = Manufacturer's Marking
PH4013SS = Product Type Marking Code
YYWW = Date Code Marking
YY = Year (ex: 20 = 2020)
WW = Week (01 to 53)



## **Maximum Ratings** (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit		
Drain-Source Voltage			VDSS	-40	V
Gate-Source Voltage			$V_{GSS}$	±20	V
Continuous Drain Current $V_{GS} = -10V$ (Note 7) Steady $T_{C} = +25^{\circ}C$ State $T_{C} = +100^{\circ}C$			lo	-69 -49	А
Pulsed Drain Current (10µs Pulse, Duty Cycle = 1%)			I <sub>DM</sub>	-277	Α
Maximum Body Diode Continuous Current (Note 7)			Is	-69	Α
Pulsed Source Current (10µs Pulse, Duty Cycle = 1%)			Ism	-277	Α
Avalanche Current (Note 8) L = 1mH			las	-22	Α
Avalanche Energy (Note 8) L = 1mH			E <sub>AS</sub>	260	mJ

#### Thermal Characteristics (@TA = +25°C, unless otherwise specified.)

Characteristic		Symbol	Value	Unit
Total Power Dissipation (Note 5)	T <sub>A</sub> = +25°C	PD	1.5	W
Thermal Resistance, Junction to Ambient (Note 5)	Steady State	$R_{\theta JA}$	98	°C/W
Total Power Dissipation (Note 6)	T <sub>A</sub> = +25°C	Pp	3.3	W
Thermal Resistance, Junction to Ambient (Note 6)	Steady State	Reja	45	°C/W
Thermal Resistance, Junction to Case (Note 7)		Rejc	1.6	°C/W
Operating and Storage Temperature Range		TJ, TSTG	-55 to +175	°C

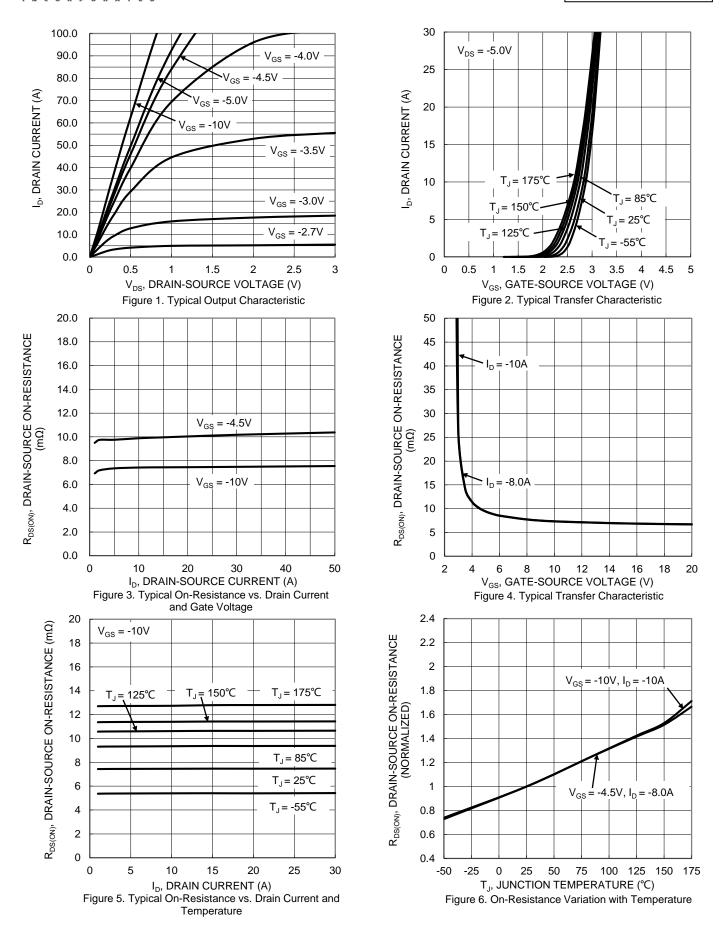
# Electrical Characteristics (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Tun	Max	Unit	Test Condition
OFF CHARACTERISTICS (Note 9)	Symbol	IVIII	Тур	IVIAX	Unit	rest Condition
` '	DV	40		T	1//	N/ 01/ 1 050::A
Drain-Source Breakdown Voltage	BVDSS	-40			V	$V_{GS} = 0V, I_{D} = -250\mu A$
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	_		-1	μΑ	$V_{DS} = -40V$ , $V_{GS} = 0V$
Gate-Source Leakage	Igss	_	_	±100	nA	$V_{GS} = \pm 20V$ , $V_{DS} = 0V$
ON CHARACTERISTICS (Note 9)						
Gate Threshold Voltage	Vgs(TH)	-1	-1.8	-3	V	$V_{DS} = V_{GS}$ , $I_D = -250\mu A$
Static Drain-Source On-Resistance	Process	_	9	13	mΩ	$V_{GS} = -10V, I_{D} = -10A$
Static Dialii-Source Off-Resistance	RDS(ON)	_	12.4	23	1115.2	$V_{GS} = -4.5V$ , $I_{D} = -8A$
Diode Forward Voltage	VsD	_	-0.70	-1.2	V	V <sub>G</sub> S = 0V, I <sub>S</sub> = -1A
DYNAMIC CHARACTERISTICS (Note 10)						
Input Capacitance	Ciss	_	4763	_		V <sub>DS</sub> = -20V, V <sub>GS</sub> = 0V f = 1MHz
Output Capacitance	Coss	_	539	_	pF	
Reverse Transfer Capacitance	C <sub>rss</sub>	_	403	_		
Gate Resistance	Rg	_	7.4	_	Ω	$V_{DS} = 0V$ , $V_{GS} = 0V$ , $f = 1MHz$
Total Gate Charge (V <sub>GS</sub> = -4.5V)	Qg	_	39	_		V <sub>DS</sub> = -20V, I <sub>D</sub> = -10A
Total Gate Charge (V <sub>GS</sub> = -10V)	Qg	_	87	_	nC	
Gate-Source Charge	Qgs	_	12.5	_	110	
Gate-Drain Charge	$Q_{gd}$	_	15	_		
Turn-On Delay Time	t <sub>D</sub> (ON)	_	6.2	_		$V_{GS} = -10V, V_{DD} = -20V,$ $R_{G} = 3\Omega, I_{D} = -10A$
Turn-On Rise Time	t <sub>R</sub>	_	4.8	_		
Turn-Off Delay Time	tD(OFF)		126		ns	
Turn-Off Fall Time	t <sub>F</sub>	_	57	_		
Reverse Recovery Time	t <sub>RR</sub>	_	27	_	ns	I <sub>F</sub> = -10A, di/dt = -100A/μs
Reverse Recovery Charge	Qrr	_	21	_	nC	I <sub>F</sub> = -10A, di/dt = -100A/μs

5. Device mounted on FR-4 PC board, with minimum recommended pad layout, single sided. Notes:

- 6. Device mounted on FR-4 substrate PC board, 2oz copper, with thermal bias to bottom layer 1inch square copper plate.
- 7. Thermal resistance from junction to soldering point (on the exposed drain pad).
- 8. I<sub>AS</sub> and E<sub>AS</sub> ratings are based on low frequency and duty cycles to keep T<sub>J</sub> = +25°C.
  9. Short duration pulse test used to minimize self-heating effect.
  10. Guaranteed by design. Not subject to product testing.







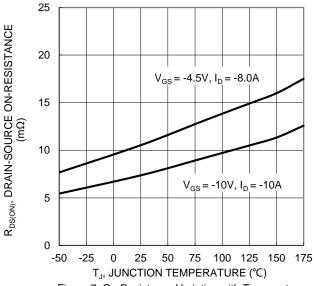
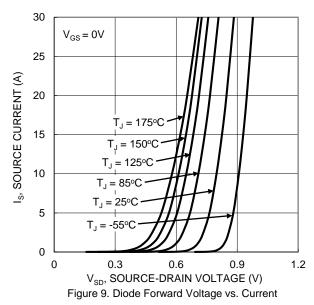
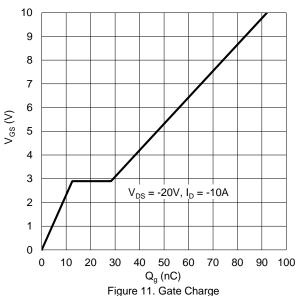


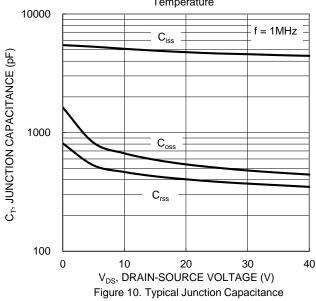
Figure 7. On-Resistance Variation with Temperature

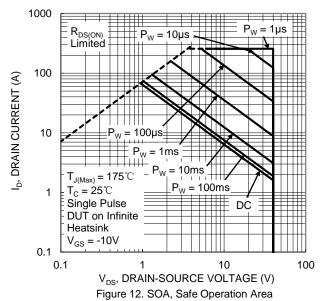




3  $V_{\text{GS(TH)}},$  GATE THRESHOLD VOLTAGE (V) 2.5  $I_D = -1mA$ 2 1.5  $I_{D} = -250 \mu A$ 1 0.5 0 -50 -25 0 75 100 125 150 175 25 50 T<sub>J</sub>, JUNCTION TEMPERATURE (°C)

Figure 8. Gate Threshold Variation vs. Junction Temperature







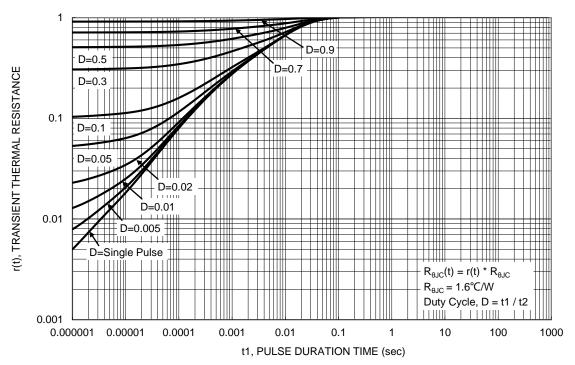


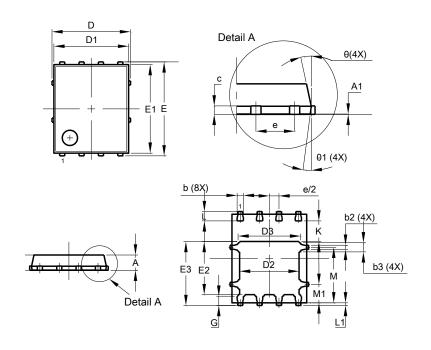
Figure 13. Transient Thermal Resistance



# **Package Outline Dimensions**

Please see http://www.diodes.com/package-outlines.html for the latest version.

#### PowerDI5060-8

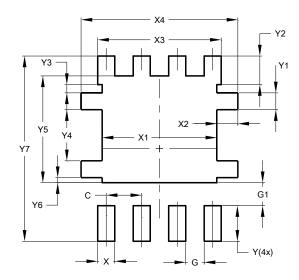


PowerDI5060-8					
Dim	Min	Тур			
Α	0.90	1.10	1.00		
<b>A</b> 1	0.00	0.05	_		
b	0.33	0.51	0.41		
b2	0.200	0.350	0.273		
b3	0.40	0.80	0.60		
С	0.230	0.330	0.277		
D	,	5.15 BSC	;		
D1	4.70	5.10	4.90		
D2	3.70	4.10	3.90		
D3	3.90	4.30	4.10		
Е	(	6.15 BSC	;		
E1	5.60	6.00	5.80		
E2	3.28	3.68	3.48		
E3	3.99	4.39	4.19		
е	1.27 BSC				
G	0.51	0.71	0.61		
K	0.51	_	-		
L	0.51	0.71	0.61		
L1	0.100	0.200	0.175		
М	3.235	4.035	3.635		
M1	1.00	1.40	1.21		
Θ	10°	12°	11°		
Θ1	6°	8°	7°		
All Dimensions in mm					

# Suggested Pad Layout

Please see http://www.diodes.com/package-outlines.html for the latest version.

#### PowerDI5060-8



Dimensions	Value (in mm)			
C	1.270			
G	0.660			
G1	0.820			
X	0.610			
X1	4.100			
X2	0.755			
Х3	4.420			
X4	5.610			
Υ	1.270			
Y1	0.600			
Y2	1.020			
Y3	0.295			
Y4	1.825			
Y5	3.810			
Y6	0.180			
Y7	6.610			



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